

### ■ Features

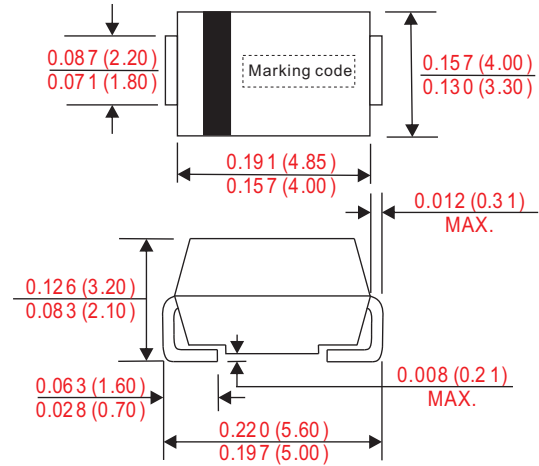
- Low profile surface mounted application in order to optimize board space.
- High current capability.
- Fast switching for high efficiency.
- High surge current capability.
- Glass passivated chip junction.
- Suffix "G" indicates Halogen free parts, ex. FS1ABG
- Lead-free parts meet environmental standards of MIL-STD-19500 /228

### ■ Mechanical data

- Epoxy: UL94-V0 rated flame retardant
- Case : Molded plastic, DO-214AA / SMB
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Weight : 0.003 ounce, 0.091 gram

### ■ Outline

SMB(DO-214AA)



Dimensions in inches and (millimeters)

### ■ Maximum ratings and electrical characteristics

Rating at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Parameter	Conditions	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	$T_L = 90^\circ\text{C}$	$I_O$			1.0	A
Forward surge current	8.3ms single half sine-wave superimposed on rate load (JEDEC method)	$I_{FSM}$			30	A
Reverse current	$V_R = V_{RRM} \quad T_A = 25^\circ\text{C}$	$I_R$			5.0	uA
	$V_R = V_{RRM} \quad T_A = 125^\circ\text{C}$				100	
Thermal resistance	Junction to ambient	$R_{\theta JA}$		50		°C/W
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	$C_J$		15		pF
Storage temperature		$T_{STG}$	-55		+150	°C

Symbol	Marking code	Max. repetitive peak reverse voltage $V_{RRM}$ (V)	Max. RMS voltage $V_{RMS}$ (V)	Max. DC blocking voltage $V_R$ (V)	Max. forward voltage @1A, $T_A = 25^\circ\text{C}$ $V_F$ (V)	Max. reverse recovery time(1) $T_{rr}$ (ns)	Operating temperature $T_J$ (°C)
FS1AB	FS1A	50	35	50	1.30	150	-55 ~ +150
FS1BB	FS1B	100	70	100			
FS1DB	FS1D	200	140	200			
FS1GB	FS1G	400	280	400		250	
FS1JB	FS1J	600	420	600			
FS1KB	FS1K	800	560	800		500	
FS1MB	FS1M	1000	700	1000			

Note : 1.  $I_F = 0.5A$ ,  $I_R = 1.0A$ ,  $I_{RR} = 0.25A$

■ Rating and characteristic curves

Fig. 1 - Forward Current Derating Curve

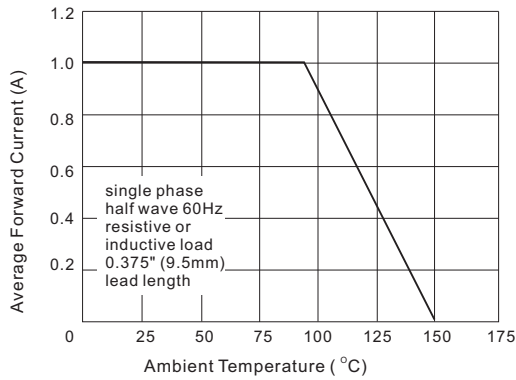


Fig. 2 - Maximum Non-Repetitive Peak Forward Surge Current

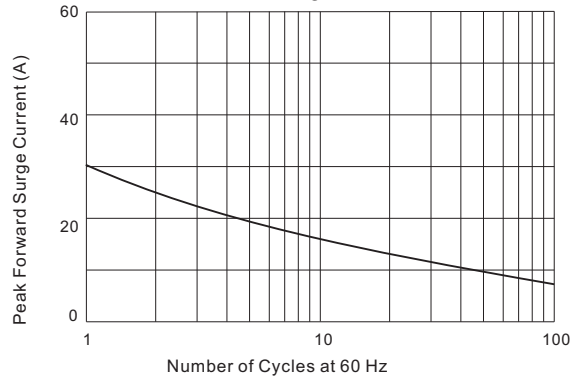


Fig. 3 - Typical Instantaneous Forward Characteristics

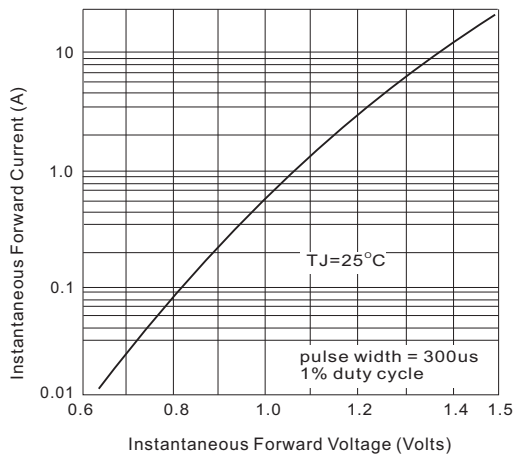


Fig. 4 - Typical Reverse Characteristics

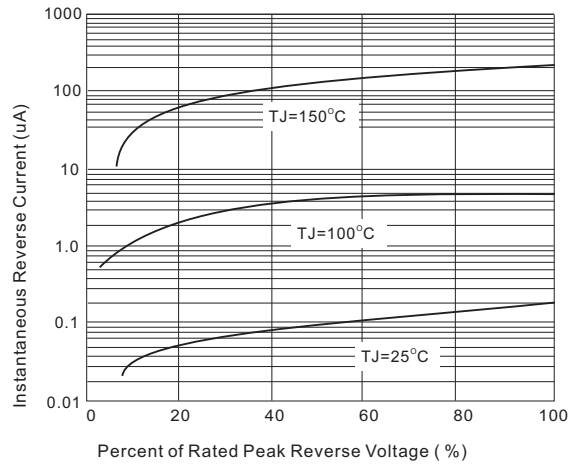
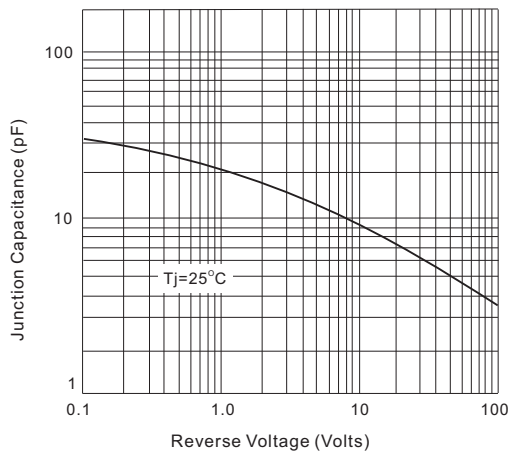
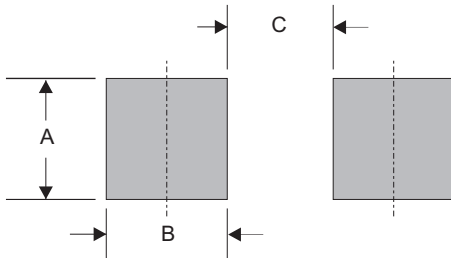


Fig. 5 - Typical Junction Capacitance



■ SMB foot print



A	B	C
0.091 (2.30)	0.098 (2.50)	0.071 (1.80)

Dimensions in inches and (millimeters)

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